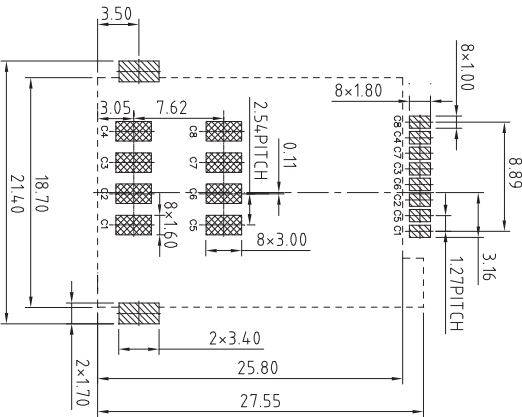
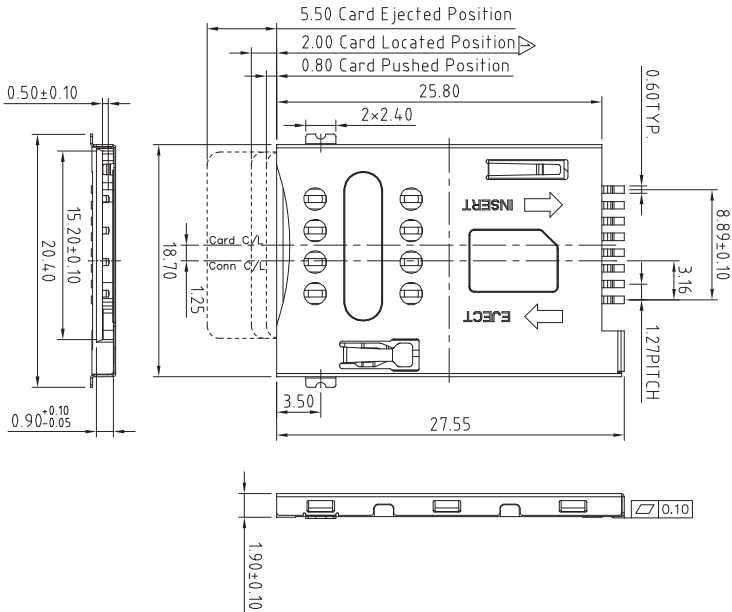
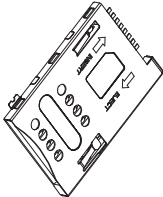


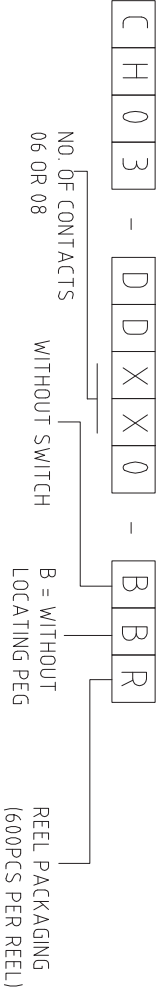
FEATURES

- 1. GENERAL CHARACTERISTICS
DIMENSIONS: 27.55L x 18.70W x 1.90H mm
WEIGHT: APPROX. 1.38g
CONTACT PRINCIPLE: FRICTION TECHNOLOGY
OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL
MOUNTING SYSTEM: SMT TYPE (without post)
FUNCTION: PUSH PUSH TYPE
DURABILITY: 5,000 CYCLES MIN.
 - 2. MECHANICAL CHARACTERISTICS
INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0
ROHS DIRECTIVE 2002/95/EC COMPLIANT
 - 3. ELECTRICAL CHARACTERISTICS
NUMBER OF CONTACTS: 6, 8 PINS (OPTIONAL)
CONTACT RESISTANCE: 50M OHMS TYP. 100M OHMS MAX.
INSULATION RESISTANCE> 1000M OHMS / 500V DC
 - 4. SOLDERABILITY
WAVE: NOT APPLICABLE
IR REFLOW: 260°C, 10 SEC. MAX.
MANUAL SOLDERING: 360°C, 3 SEC. MAX.
 - 5. ENVIRONMENTAL CHARACTERISTICS
OPERATING TEMPERATURE: -40°C ~ +85°C
OPERATING HUMIDITY: 10% ~ 95% RH
STORAGE TEMPERATURE: -40°C ~ +85°C
STORAGE HUMIDITY: 10% ~ 95% RH
- NOTES:
1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.



Legend: [Hatched Box] BOARD PAD [Cross-hatched Box] NO WIRING AREA
UNIT: MM; TOLERANCES: ±0.05 MM
REFERENCE DIMENSION FOR PCB LAYOUT

HOW TO ORDER



REV. DATE & DRN									
10 18/06/09-CHC RELEASE									
11 04/01/13 - NYW AMEND DISCRPTION.									
12 01/12/14 - NYW REMOVE WITH PEG OPTION.									